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Nota di contenuto	Macromodeling of Complex Interconnects in 3D Integration -- 2.5D Simulation Method for 3D Integrated Systems -- Hybrid Integral Equation Modeling Methods for 3D Integration -- Systematic Microwave Network Analysis for 3D Integrated Systems -- Modeling of Through-Silicon Vias (TSV) in 3D Integration.
Sommario/riassunto	New advanced modeling methods for simulating the electromagnetic properties of complex three-dimensional electronic systems Based on the author's extensive research, this book sets forth tested and proven electromagnetic modeling and simulation methods for analyzing signal and power integrity as well as electromagnetic interference in large complex electronic interconnects, multilayered package structures, integrated circuits, and printed circuit boards. Readers will discover the

state of the technology in electronic package integration and printed circuit board simulation and